

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>PU WANG</td> <td>11/12/2013</td> </tr> <tr> <td>YING-CHING SHIH</td> <td>11/12/2013</td> </tr> <tr> <td>SZU WEI LU</td> <td>11/12/2013</td> </tr> <tr> <td>JING-CHENG LIN</td> <td>11/12/2013</td> </tr> </tbody> </table>		Name	Execution Date	PU WANG	11/12/2013	YING-CHING SHIH	11/12/2013	SZU WEI LU	11/12/2013	JING-CHENG LIN	11/12/2013
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PU WANG	11/12/2013										
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SZU WEI LU	11/12/2013										
JING-CHENG LIN	11/12/2013										
RECEIVING PARTY DATA											
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.										
Street Address:	No. 8, Li-Hsin Rd. 6										
Internal Address:	Science-Based Industrial Park										
City:	Hsin-Chu										
State/Country:	TAIWAN										
Postal Code:	300-77 R.O.C.										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14081853</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14081853						
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Application Number:	14081853										
CORRESPONDENCE DATA											
Fax Number:	(972)732-9218										
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NAME OF SUBMITTER:	CLAUDETTE L. HOFFMANN										

CH \$40.00 14081853

Signature:	/Claudette L. Hoffmann/
Date:	12/05/2013
Total Attachments: 1 source=TSM13-1086 Signed Assignment#page1.tif	

ATTORNEY DOCKET NO.  
TSM13-1086

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and





WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Fan Out Package Structure and Methods of Forming			
SIGNATURE OF INVENTOR AND NAME	 Pu Wang	 Ying-Ching Shih	 Szu Wei Lu	 Jing Cheng Lin
DATE	2013-11-12	2013, 11, 12	11/12 '13	2013.11.12
RESIDENCE	Hsin-Chu, Taiwan	Taipei City, Taiwan	Hsin-Chu, Taiwan	Chu Tung Zhen, Taiwan